



UNION INKS

Product Information

PEELABLE MASK BLUE

99-88

APPLICATION AND END-USE DESIGN

Peel able Mask 99-88 is specially formulated to provide temporary protection for selected board areas against hot air levelling, wave soldering and gold plating. It's high heat resistance properties is ideal for lead free solder paste and soldering process. It is used as an alternative to the otherwise laborious process of masking board areas by tape against unwanted solder pick up or galvanic deposit.

Peelable Mask 99-88B is suitable for use over 99-PC37 / 1 Carbon Conductor Pastes.

FEATURES AND ADVANGTAGES

Plating Resist - 99-88B can be used as a localised resist protecting parts of the circuit board during plating of the rest of the circuit.

Solder Resist - 99-88B is formulated to resist soldering operations including lead free soldering (always pretest before production runs) and will withstand wave soldering at 250 - 260 °C for 5 seconds. It may be used: -

- i) To protect gold fingers and contact pads during HASL or wave soldering of the rest of the boards.
- ii) To protect conductors during soldering of the rest of the boards.
- iii) Ideal for IR reflow boards.

PROCESSING NOTES

VISCOSITY ADJUSTMENTS

99-88 is supplied at printing viscosity and should not need any viscosity adjustment. The addition of solvent is not recommended since this may cause a reduction in film strength and poor peeling properties.

PRE-CLEANING OF BOARDS

Boards should be free from oil, grease and other surface contaminants prior to application of the resist.

PRINTING

Mesh: Use polyester monofilament of 11 - 24T per cm to ensure a thick, even and pinhole-free film.

Stencils: Capillary film or direct emulsions are recommended to achieve a stencil thickness of 50 - 100 microns.

Squeegee: When printing over tracks, it is better to use squeegee of 60 - 65 shore hardness at a relatively flat angle to ensure complete coverage with minimal deposit into holes.

When printing on both sides of the boards, it is important to ensure that the two layers of the resist do not join through a hole or removal maybe difficult.

CURING

Correct curing of 99-88 is important, since it determines the forming of the continuous film and prevents porosity and lack of chemical resistant as well as easy peel ability.

TYPICAL CURE SCHEDULE:

Conventional oven: 20 - 30 minutes at 145 - 150 °C.

Infrared conveyor oven: 4 - 5 minutes at 180 °C.

REMOVAL

99-88 is removed by peeling from the board; this is easiest if the edge of the film has a sharp profile. This can be achieved by the use of thick stencils. Poor peeling may result if the film has been inadequately cured or if the solvent has been added.

SCREEN CLEANING

Screens should be clean using Universal Screen wash 99-SW113.

STORAGE

Store at 25 °C in a dry store. Avoid subjecting containers to high temperature as this shortened the shelf life.

SHELF LIFE

Six months from date of manufacture when store in cool dry conditions.

WARNING

This information is given in good faith, but without any guarantee as the printing conditions of our inks are beyond our control. In the event of complaints, the ink supplier may replace free of charge the unused ink, declining any other responsibilities.